



Material Content Data Sheet



Halogen-Free

Sales Product Name	ISZ0703NLS	Issued	18. August 2021
MA#	MA005423485		
Package	PG-TSDSON-8-25	Weight*	35.44 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.294	0.83	0.83	8282	8282
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		69	
	non noble metal	zinc	7440-66-6	0.010	0.03		278	
	non noble metal	iron	7439-89-6	0.197	0.56		5552	
	non noble metal	copper	7440-50-8	7.988	22.54	23.14	225425	231324
wire	noble metal	gold	7440-57-5	0.028	0.08	0.08	785	785
encapsulation	organic material	carbon black	1333-86-4	0.038	0.11		1076	
	plastics	epoxy resin	-	1.964	5.54		55413	
	inorganic material	silicondioxide	60676-86-0	17.063	48.13	53.78	481500	537989
leadfinish	non noble metal	tin	7440-31-5	0.395	1.12	1.12	11154	11154
plating	noble metal	silver	7440-22-4	0.020	0.06	0.06	573	573
solder	non noble metal	tin	7440-31-5	0.010	0.03		274	
	noble metal	silver	7440-22-4	0.012	0.03		343	
	non noble metal	lead	7439-92-1	0.464	1.31	1.37	13085	13702
heat sink clip	inorganic material	phosphorus	7723-14-0	0.001			26	
	non noble metal	zinc	7440-66-6	0.004	0.01		103	
	non noble metal	iron	7439-89-6	0.073	0.21		2057	
	non noble metal	copper	7440-50-8	2.959	8.35	8.57	83505	85691
heatspreader	inorganic material	phosphorus	7723-14-0	0.001			33	
	non noble metal	zinc	7440-66-6	0.005	0.01		133	
	non noble metal	iron	7439-89-6	0.094	0.27		2652	
	non noble metal	copper	7440-50-8	3.816	10.77	11.05	107682	110500
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com

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